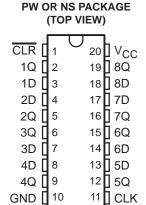
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- Controlled Baseline
  - One Assembly/Test Site, One Fabrication Site
- Enhanced Diminishing Manufacturing Sources (DMS) Support
- Enhanced Product-Change Notification
- Qualification Pedigree<sup>†</sup>
- Supports Mixed-Mode Signal Operation (5-V Input and Output Voltages With 3.3-V V<sub>CC</sub>)
- Typical V<sub>OLP</sub> (Output Ground Bounce)
   <0.8 V at V<sub>CC</sub> = 3.3 V, T<sub>A</sub> = 25°C
- Supports Unregulated Battery Operation Down to 2.7 V
- Buffered Clock and Direct-Clear Inputs
- Individual Data Input to Each Flip-Flop
- I<sub>off</sub> Supports Partial Power-Down-Mode Operation

† Component qualification in accordance with JEDEC and industry standards to ensure reliable operation over an extended temperature range. This includes, but is not limited to, Highly Accelerated Stress Test (HAST) or biased 85/85, temperature cycle, autoclave or unbiased HAST, electromigration, bond intermetallic life, and mold compound life. Such qualification testing should not be viewed as justifying use of this component beyond specified performance and environmental limits.

- Bus Hold on Data Inputs Eliminates the Need for External Pullup/Pulldown Resistors
- Latch-Up Performance Exceeds 500 mA Per JESD 17
- ESD Protection Exceeds JESD 22
  - 2000-V Human-Body Model (A114-A)
  - 200-V Machine Model (A115-A)



#### description/ordering information

This octal D-type flip-flop is designed specifically for low-voltage (3.3 V)  $V_{CC}$  operation, but with the capability to provide a TTL interface to a 5-V system environment.

The SN74LVTH273 is a positive-edge-triggered flip-flop with a direct clear  $(\overline{CLR})$  input. Information at the data (D) inputs meeting the setup-time requirements is transferred to the Q outputs on the positive-going edge of the clock pulse. Clock triggering occurs at a particular voltage level and is not related directly to the transition time of the positive-going pulse. When the clock (CLK) input is at either the high or low level, the D-input signal has no effect at the output.

Active bus-hold circuitry holds unused or undriven inputs at a valid logic state. Use of pullup or pulldown resistors with the bus-hold circuitry is not recommended.

This device is fully specified for partial power-down applications using  $I_{off}$ . The  $I_{off}$  circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.

#### ORDERING INFORMATION

TA	PACK	AGE <sup>‡</sup>	ORDERABLE PART NUMBER	TOP-SIDE MARKING
-40°C to 85°C	TSSOP – PW Tape and reel		SN74LVTH273IPWREP	LH273EP
-55°C to 125°C	SOP - NS	Tape and reel	SN74LVTH273MNSREP	LVTH273EP

<sup>‡</sup> Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

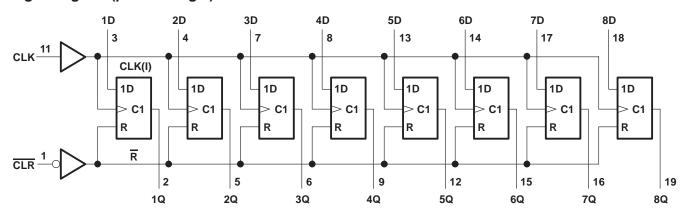


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## FUNCTION TABLE (each flip-flop)

	INPUTS	OUTPUT	
CLR	CLK	D	Q
L	Х	Χ	L
Н	$\uparrow$	Н	Н
Н	$\uparrow$	L	L
Н	H or L	Χ	$Q_0$

#### logic diagram (positive logic)



### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V <sub>CC</sub> –0.5	V to 4.6 V
Input voltage range, V <sub>I</sub> (see Note 1)	.5 V to 7 V
Voltage range applied to any output in the power-off state, V <sub>O</sub> (see Note 1)	.5 V to 7 V
Voltage range applied to any output in the high state, V <sub>O</sub> (see Note 1)0.5 V to V <sub>O</sub>	CC + 0.5 V
Current into any output in the low state, IO	128 mA
Current into any output in the high state, IO (see Note 2)	64 mA
Input clamp current, I <sub>IK</sub> (V <sub>I</sub> < 0)	–50 mA
Output clamp current, I <sub>OK</sub> (V <sub>O</sub> < 0)	–50 mA
Package thermal impedance, θ <sub>JA</sub> (see Note 3): NS package	94.4°C/W
PW package	83°C/W
Storage temperature range, T <sub>stg</sub> –65°C	C to 150°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
  - 2. This current flows only when the output is in the high state and  $V_O > V_{CC}$ .
  - 3. The package thermal impedance is calculated in accordance with JESD 51-7.
  - 4. Long-term high-temperature storage and/or extended use at maximum recommended operating conditions may result in a reduction of overall device life. See http://www.ti.com/ep\_quality for additional information on enhanced plastic packaging.



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### recommended operating conditions (see Note 4)

			MIN	MAX	UNIT
Vcc	Supply voltage		2.7	3.6	V
VIH	High-level input voltage	2		V	
V <sub>IL</sub>	Low-level input voltage		8.0	V	
VI	Input voltage				V
IOH	High-level output current				mA
loL	Low-level output current			64	mA
Δt/Δν	Input transition rise or fall rate				ns/V
Τ.	Operating free air temperature	SN74LVTH273I		85	°C
TA	Operating free-air temperature	SN74LVTH273M	-55	125	-0

NOTE 5: All unused control inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. See the TI application report, *Implications of Slow or Floating CMOS Inputs* (SCBA004).

## electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

				SN74	LVTH27	31	SN74	LVTH273	M		
PA	RAMETER	TEST CONDITIO	ONS	MIN	TYP <sup>†</sup>	MAX	MIN	TYP <sup>†</sup>	MAX	UNIT	
VIK		$V_{CC} = 2.7 \text{ V}, I_{I} = -18 \text{ mA}$				-1.2			-1.2	V	
		$V_{CC} = 2.7 \text{ V to } 3.6 \text{ V, } I_{OH} = -$	V <sub>CC</sub> -0.2			V <sub>CC</sub> -0.2					
Vон		$V_{CC} = 2.7 \text{ V, } I_{OH} = -8 \text{ mA}$		2.4			2.4			V	
		$V_{CC} = 3 \text{ V, } I_{OH} = -32 \text{ mA}$		2			2				
		V 0.7V	I <sub>OL</sub> = 100 μA			0.2			0.2		
		V <sub>CC</sub> = 2.7 V	$I_{OL} = 24 \text{ mA}$			0.5			0.5		
$V_{OL}$			I <sub>OL</sub> = 16 mA			0.4			0.4	V	
		V <sub>CC</sub> = 3 V	$I_{OL} = 32 \text{ mA}$			0.5			0.5		
			I <sub>OL</sub> = 64 mA			0.55			0.55		
		$V_{CC} = 0 \text{ or } 3.6 \text{ V}, V_{I} = 5.5 \text{ V}$				10			12		
	Control inputs	$V_{CC} = 3.6 \text{ V}, V_I = V_{CC} \text{ or GN}$			±1			±2	•		
I <sub>I</sub>	Data insuta	V 20V	VI = VCC			1			1	μΑ	
	Data inputs	VCC = 3.6 V	V <sub>I</sub> = 0			-5			-5		
l <sub>off</sub>		$V_{CC} = 0$ , $V_{I}$ or $V_{O} = 0$ to 4.5	V			±100			±100	μΑ	
		V 2V	V <sub>I</sub> = 0.8 V	75			75				
11/11-1	Data inputs	V <sub>CC</sub> = 3 V	V <sub>I</sub> = 2 V	-75			-75			μΑ	
I(hold)	Data Inputs	$V_{CC} = 3.6 \text{ V}^{\ddagger}, V_{I} = 0 \text{ to } 3.6 \text{ V}$			500 -750			500 -750	μΑ		
		V <sub>CC</sub> = 3.6 V, I <sub>O</sub> = 0,	Outputs high			0.19			0.19		
ICC		$V_I = V_{CC}$ or GND	Outputs low		5			5	mA		
ΔI <sub>CC</sub> §		V <sub>CC</sub> = 3 V to 3.6 V, One input Other inputs at V <sub>CC</sub> or GND	at V <sub>CC</sub> – 0.6 V,			0.2			0.2	2 mA	
Ci		V <sub>I</sub> = 3 V or 0			4			4		pF	

<sup>&</sup>lt;sup>†</sup> All typical values are at  $V_{CC} = 3.3 \text{ V}$ ,  $T_A = 25^{\circ}\text{C}$ .



<sup>‡</sup> This is the bus-hold maximum dynamic current. It is the minimum overdrive current required to switch the input from one state to another.

<sup>§</sup> This is the increase in supply current for each input that is at the specified TTL voltage level, rather than VCC or GND.

### SN74LVTH273-EP 3.3-V ABT OCTAL D-TYPE FLIP-FLOP WITH CLEAR

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## timing requirements over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

			V <sub>CC</sub> =	3.3 V 3 V	VCC =	2.7 V	UNIT	
			MIN	MAX	MIN	MAX		
fclock	Clock frequency		150			MHz		
t <sub>W</sub>	Pulse duration		3.3		3.3		ns	
	0	Data high or low before CLK↑	2.3		2.7			
tsu	Setup time	CLR high before CLK↑	2.3		2.7		ns	
t <sub>h</sub>	Hold time, data high or low after CLK↑		0		0		ns	

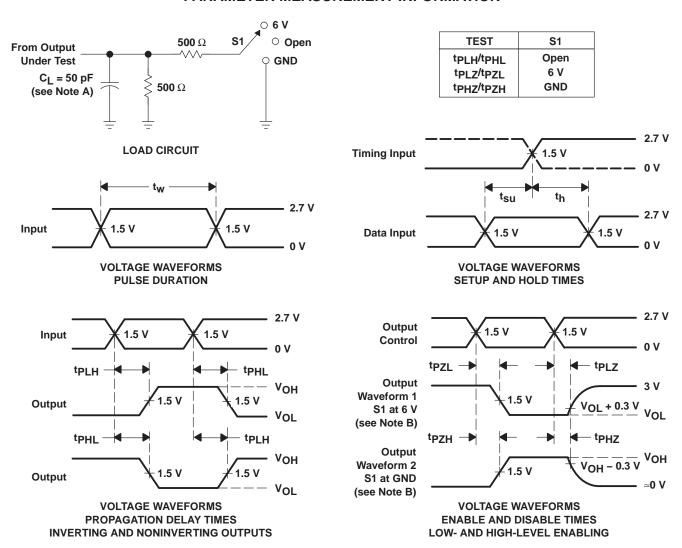
# switching characteristics over recommended operating free-air temperature range, $C_L = 50 \text{ pF}$ (unless otherwise noted) (see Figure 1)

							H273I	SN74LVT		
PARAMETER	FROM (INPUT)	TO (OUTPUT)	TO V <sub>CC</sub> = 3.3 V ±0.3 V		V <sub>CC</sub> = 2.7 V		V <sub>CC</sub> = 2.7 V		UNIT	
	(1141 01)	(001101)	MIN	TYP <sup>†</sup>	MAX	MIN	MAX	MIN	MAX	
f <sub>max</sub>			150							MHz
tPLH	CLK	A O	1.7	3.2	4.9		5.5		7	
t <sub>PHL</sub>	CLK	Any Q	1.9	3.2	4.8		5.1		6.6	ns
tPHL	CLR	Any Q	1.6	2.7	4.3		4.7		7	ns

<sup>&</sup>lt;sup>†</sup> All typical values are at  $V_{CC}$  = 3.3 V,  $T_A$  = 25°C.



#### PARAMETER MEASUREMENT INFORMATION



NOTES: A. C<sub>I</sub> includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz,  $Z_Q = 50 \ \Omega$ ,  $t_f \leq 2.5 \ ns$ .
- D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

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#### PACKAGING INFORMATION

Orderable part number	Status (1)	Material type	Package   Pins	Package qty   Carrier	<b>RoHS</b> (3)	Lead finish/ Ball material	MSL rating/ Peak reflow	Op temp (°C)	Part marking (6)
CLVTH273MNSREPG4	Active	Production	SOP (NS)   20	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	LVTH273EP
SN74LVTH273MNSREP	Active	Production	SOP (NS)   20	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	LVTH273EP
V62/04674-02YE	Active	Production	SOP (NS)   20	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	LVTH273EP

<sup>(1)</sup> Status: For more details on status, see our product life cycle.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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#### OTHER QUALIFIED VERSIONS OF SN74LVTH273-EP:

Catalog: SN74LVTH273

<sup>(2)</sup> Material type: When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

<sup>(3)</sup> RoHS values: Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

<sup>(4)</sup> Lead finish/Ball material: Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

<sup>(5)</sup> MSL rating/Peak reflow: The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

<sup>(6)</sup> Part marking: There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.



## **PACKAGE OPTION ADDENDUM**

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NOTE: Qualified Version Definitions:

 $_{\bullet}$  Catalog - TI's standard catalog product

## **PACKAGE MATERIALS INFORMATION**

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#### TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

#### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



#### \*All dimensions are nominal

Device	_	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LVTH273MNSREP	SOP	NS	20	2000	330.0	24.4	8.4	13.0	2.5	12.0	24.0	Q1

## **PACKAGE MATERIALS INFORMATION**

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#### \*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LVTH273MNSREP	SOP	NS	20	2000	356.0	356.0	45.0

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